

## CALL FOR PAPERS

## **ORGANIZERS**

#### **GENERAL CHAIRS**

Andy Chen REDDS Capital, Canada

Tariq Samad

University of Minnesota, US

**PROGRAM CHAIR** 

Tugrul Daim

Portland State University, US

**FINANCE CHAIR** 

**Robert Bierwolf** 

MinBzk, Netherlands

**INDUSTRY CHAIR** 

**Gustavo Giannattasio** 

IEEE TEMS, Uruguay

**ENTREPRENEURSHIP CHAIR** 

Binesh Kumar

Atom Power, US

WORKSHOP CHAIR

Noorlizawati Abd-Rahim

UTM, Malaysia

LOCAL ARRANGEMENTS CHAIRS

Marine Agogué

HEC Montreal, Canada

Romain Rampa

École de Technologie Supérieure, Canada

See the conference website for the full **Operating Committee** 

## **DEADLINES**

INVITED SESSION PROPOSALS

**January 15, 2026** 

SHORT & FULL PAPER SUBMISSION

February 15, 2026

**WORKSHOP PROPOSALS** 

February 15, 2026

NOTIFICATION OF ACCEPTANCE

April 15, 2026

FINAL PAPER SUBMISSION

June 1, 2026

## **VENUE**

DOUBLETREE BY HILTON MONTRÉAL



Today's world has been profoundly shaped by technological innovation. The scale and impact of technology on tomorrow's world will be even greater, with attendant opportunities as well as predicaments arising from disruptive developments in areas such as artificial intelligence, quantum computing, and blockchain. From addressing societal challenges to meeting industry needs to facilitating entrepreneurial ventures, addressing imperatives of today and tomorrow will crucially rely on technology management and leadership.

TEMSCON Global is the flagship conference of the IEEE Technology and Engineering Management Society (TEMS) and is a premier venue for research on management, innovation, and leadership across the spectrum of technology, science, and engineering. The conference will convene researchers, managers, practitioners, educators, students, and policy makers to present and discuss new developments in the fields of interest of IEEE TEMS. The conference program will include contributions to this call for papers as well as plenary lectures, entrepreneurship sessions, and industry forums.

#### SUBMISSIONS FOR THE TEMSCON GLOBAL PROGRAM

TEMSCON Global welcomes submissions of full papers and short papers. Manuscripts that are accepted and presented will be submitted for inclusion in the IEEE Xplore® digital library and indexed by EI/Compendex. Authors of selected papers will be invited to submit extended versions for potential publication in special issues of IEEE Transactions on Engineering Management and IEEE Engineering Management Review. Proposals for workshops and invited sessions are also welcome. Refer to the conference website for further details and submission instructions.

## TOPICS OF INTEREST (PARTIAL LIST)

#### **MANAGEMENT OF TECHNOLOGIES**

- » Agentic and generative AI
- » Machine learning and data analytics
- » Edge and cloud computing
- » Blockchain and distributed ledgers
- » Cybersecurity and quantum

# TECHNOLOGY AND BUSINESS STRATEGY

- » Management of engineering organizations
- » Innovation and entrepreneurship
- » R&D and NPD management
- » Supply chain and operations
- » Digital transformation

## SOCIETAL AND INDUSTRY APPLICATIONS

- » Aerospace and defense
- » Software and services
- » Sustainability and climate change
- » Smart cities and infrastructure
- » Smart manufacturing and logistics

#### **GOVERNANCE AND POLICY**

- » Science and technology policy
- » Regulation and compliance
- » Ethics of artificial intelligence
- » National industrial policy
- » Technology transfer





